FUZETEC TECHNOLOGY CO., LTD.

PQ15-101E

NO.

Product Specification and Approval Sheet Version 1/3

A2

Radial Leaded PTC Resettable Fuse: FRT Series

1. Summary

- (a) RoHS Compliant (Lead Free) Product
- (b) Applications: IEEE 1394 FireWire, Computers & Consumer electronics
- (c) Product Features: Fast trip time, Lower Trip-to-hold Ratio, Radial-leaded product ideal for up to 36VDC
- (d) Operation Current: 0.50A~2.50A
- (e) Maximum Voltage: 36VDC
- (f) Temperature Range : -40° C to 85° C

2. Agency Recognition

- UL: File No. E211981
- C-UL: File No. E211981

TÜV: File No. R50004084

3. Electrical Characteristics (23°C)

Part Number	Hold	Trip	Max.Time	Max.	Rated	Тур.	Typ. Resistance			
	Current	Current	To Trip	Current	Voltage	Power	RMIN	R1max		
	Ін, А	Ιт, А	at 5xIH,s	IMAX, A	VMAX, VDC	Pd, W	Ohms	Ohms		
FRT050-33F	0.50	1.10	5.0	40	36	0.67	0.140	0.448		
FRT075-33F	0.75	1.50	4.0	40	36	0.71	0.115	0.368		
FRT090-33F	0.90	1.80	3.5	40	36	0.74	0.090	0.288		
FRT120-33F	1.20	2.30	3.5	40	36	0.78	0.074	0.180		
FRT135-33F	1.35	2.50	4.5	40	36	0.84	0.059	0.143		
FRT160-33F	1.60	2.75	4.5	40	36	0.86	0.041	0.131		
FRT190-33F	1.90	3.00	3.5	40	36	0.90	0.045	0.092		
FRT220-33F	2.20	3.50	6.5	40	36	0.95	0.025	0.080		
FRT250-33F	2.50	4.00	8.0	40	36	0.99	0.020	0.064		

IH=Hold current-maximum current at which the device will not trip at 23°C still air.

IT=Trip current-minimum current at which the device will always trip at 23 $^{\circ}$ C still air. V_{MAX}=Maximum voltage device can withstand without damage at its rated current.

I MAX= Maximum fault current device can withstand without damage at rated voltage (V MAX).

Pd=Typical power dissipated from device when in tripped state in 23 °C still air environment.

RMIN=Minimum device resistance at 23°C

R1_{MAX}=Maximum device resistance at 23°C, 1 hour after tripping.

Physical specifications:

Lead material: Tin plated copper clad steel, 24 AWG. Soldering characteristics:MIL-STD-202, Method 208E.

Insulating coating:Flame retardant epoxy, meets UL-94V-0 requirement.

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4. Production Dimensions (millimeter)



Lead Size :24AWG Φ 0.51 mm Diameter

Part	Α	В	С	D	E	F	
Number	Maximum	Maximum	Typical	Minimum	Maximum	Typical	
FRT050-33F	7.4	12.2	5.1	7.6	3.0	1.1	
FRT075-33F	7.4	12.2	5.1	7.6	3.0	1.1	
FRT090-33F	7.4	12.2	5.1	7.6	3.0	1.1	
FRT120-33F	7.4	12.2	5.1	7.6	3.0	1.1	
FRT135-33F	7.4	14.2	5.1	7.6	3.0	1.1	
FRT160-33F	7.4	14.0	5.1	7.6	3.0	1.1	
FRT190-33F	9.0	13.5	5.1	7.6	3.0	1.1	
FRT220-33F	10.0	17.0	5.1	7.6	3.0	1.1	
FRT250-33F	10.0	19.5	5.1	7.6	3.0	1.1	

5. Thermal Derating Curve



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6. Typical Time-To-Trip at 23℃



7. Material Specification

Lead material : Tin plated copper clad steel, 24 AWG. Soldering characteristics: MIL-STD-202, Method 208E. Insulating coating:Flame retardant epoxy, meets UL-94V-0 requirement.

8. Part Numbering and Marking System



RoHS Compliant / Lead Free Part Identification Product Family

Fuzetec Logo

Date Code/Lot Number

Note: Font on Marking may look slightly different due to fine turnings of each Marking printer.

Warning: - Each product should be carefully evaluated and tested for their suitability of application.

- Operation beyond the specified maximum rating or improper use may result in damage and possible electrical arcing and/or flame.
- PPTC device are intended for occasional overcurrent protection. Application for repeated overcurrent condition and/or prolonged trip are not anticipated.
- Avoid contact of PPTC device with chemical solvent, including some inert material such as silicone based oil, lubricant and etc. Prolonged contact will damage the device performance.
- Additional protection mechanism are strongly recommended to be used in conjunction with the PPTC device for protection against abnormal or failure conditions.
- Avoid use of PPTC device in a constrained space such as potting material, housing and containers where have limited space to accommodate device thermal expansion and/or contraction.4/

NOTE : Specification subject to change without notice.